

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:

CORRECTIVE ASSIGNMENT

NATURE OF CONVEYANCE:

Corrective Assignment to correct the Spelling of inventor name previously recorded on Reel 015070 Frame 0726. Assignor(s) hereby confirms the Konda, Akihiko.

CONVEYING PARTY DATA

Name	Execution Date
Akihiko Kondo	07/30/2003
Hideki Fukuda	07/30/2003
Takeshi Matsumoto	07/30/2003
Hideo Noda	07/31/2003

RECEIVING PARTY DATA

Name:	Kansai Chemical Engineering, Co., Ltd.
Street Address:	9-7 Minaminanamatsucho 2-Chome
Internal Address:	Amagasaki-Shi
City:	Hyogo
State/Country:	JAPAN
Postal Code:	600-0053

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	10474431

CORRESPONDENCE DATA

Fax Number: (703)591-5907  
*Correspondence will be sent via US Mail when the fax attempt is unsuccessful.*  
Phone: 703-591-2664  
Email: janet.wright.@jagtiani.com  
Correspondent Name: Ajay Jagtiani  
Address Line 1: 10363-A Democracy Lane  
Address Line 4: Fairfax, VIRGINIA 22030

NAME OF SUBMITTER:

Ajay Jagtiani

Total Attachments: 4

PATENT

500007864

REEL: 015182 FRAME: 0972

CH \$40.00 10474431

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source=NANJ-0008-1 10,474,431 (TM)pdf#page1.tif

### ASSIGNMENT

WHEREAS, **HIDEKI FUKUDA, AKHIKO KONDO AND TAKESHI MATSUMOTO**, whose post office addresses appear below (hereinafter referred to as **ASSIGNOR**), have invented certain new and useful improvements in an **CELL SURFACE LAYER-BINDING PROTEIN AND UTILIZATION THEREOF** (hereinafter referred to as **THE INVENTION**) for which an application for United States Letters Patent was filed concurrently herewith, Serial Number: \_\_\_\_\_;

WHEREAS, **KANSAI CHEMICAL ENGINEERING CO., LTD.**, whose post office address is **9-7, Minaminanamatsucho 2-chome, Amagasaki-shi, Hyogo 660-0053 JAPAN**, (hereinafter referred to as **ASSIGNEE**), is desirous of acquiring the entire right, title and interest in and to the same in the United States and throughout the world;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, we, **ASSIGNOR**, by these presents do sell, assign and transfer until said **ASSIGNEE**, the entire right, title and interest in and to said invention and application throughout the United States of America, including any and all United States Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application; and the entire right, title and interest in and to said invention throughout the world, including the right to apply for patents and inventor certificates in respect thereof and to claim priority pursuant to rights accorded **ASSIGNOR** under the terms of the Paris International Convention and all other available international conventions and treaties; and the entire right, title and interest in and to any and all patents, patents of addition, utility models, patents of importation, revalidation patents and inventor certificates which may be granted throughout the world in respect of said invention.

ALSO, **ASSIGNOR** hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) or inventor certificate(s) in the United States and in foreign countries for said invention, including additional documents that may be required to affirm the rights of **ASSIGNEE** in and to said invention, all without further consideration. **ASSIGNOR** also agrees, without further consideration and at **ASSIGNEE**'s expense, to identify and communicate to **ASSIGNEE** at **ASSIGNEE**'s request documents and information concerning the invention that are within **ASSIGNOR**'s possession or control, and to provide further assurances and testimony on behalf of **ASSIGNEE** that lawfully may be required of **ASSIGNOR** in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument.

**ASSIGNOR** also agrees, without further consideration and at **ASSIGNEE**'s expense, to transfer the right to sue for past infringement to **ASSIGNEE** and at **ASSIGNEE**'s request documents and information concerning the enforcement of the right to sue within **ASSIGNOR**'s possession or control, and to provide further assurances and testimony on behalf of **ASSIGNEE** that lawfully may be required of **ASSIGNOR** in respect of the right to sue of any patent encompassed within the terms of this instrument.

**ASSIGNOR**'s obligations under this instrument shall extend to **ASSIGNOR**'s heirs, executors, administrators and other legal representatives.

**ASSIGNOR** hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent referred to above to **ASSIGNEE** of the entire right, title and interest in and to the same, for **ASSIGNEE**'s sole use and behalf; and for the use and behalf of **ASSIGNEE**'s legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by **ASSIGNOR** had this assignment and sale not been made.

Mr. Hideki FUKUDA  
8-13, Syofuudai 1-chome, Tarumi-ku, Kobe-shi,  
Hyogo 655-0871 JAPAN



Signature

Date: July 30, 2003

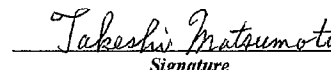
Mr. Akihiko KONDO  
1-2-806, Shinoharaobanoyamacho 1-chome,  
Nada-ku, Kobe-shi, Hyogo 657-0015 JAPAN



Signature

Date: July 30, 2003

Mr. Takeshi MATSUMOTO  
Room 308, Koyo Haitsu, 8-21, Shinoharadai,  
Nada-ku, Kobe-shi, Hyogo 657-0016 JAPAN



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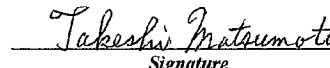
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Room 308, Koyo Haitsu, 8-21, Shinoharadai,  
Nada-ku, Kobe-shi, Hyogo 657-0016 JAPAN



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Date:

**ASSIGNMENT**

WHEREAS, **HIDEO NODA**, whose post office addresses appear below (hereinafter referred to as ASSIGNOR), have invented certain new and useful improvements in an **CELL SURFACE LAYER-BINDING PROTEIN AND UTILIZATION THEREOF** (hereinafter referred to as **THE INVENTION**) for which an application for United States Letters Patent was filed concurrently herewith, Serial Number: \_\_\_\_\_;

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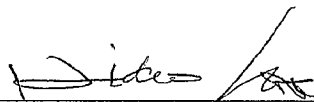
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Mr. Hideo NODA

9-7, Minaminanamatsucho 2-chome, Amagasaki-shi,  
Hyogo 660-0053 JAPAN

  
\_\_\_\_\_  
Signature

Date: July 31, 2003

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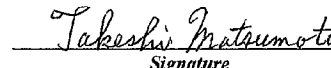
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